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# **INFORMATION DISCLOSURE STATEMENT BY APPLICANT** ( Not for submission under 37 CFR 1.99)

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|------------------------|-------------------------|
| Application Number     | 10542040                |
| Filing Date            | 2006-02-06              |
| First Named Inventor   | John Mize               |
| Art Unit               | 1795                    |
| Examiner Name          | Jason Berman            |
| Attorney Docket Number | H0004870.70759 US -4015 |

## **U.S.PATENTS**

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